

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ELECTRONIC SURFACE MOUNT PACKAGE WITH EXTENDED SIDE RETAINING WALL, the specification of which:

(check is attached hereto one)

was filed on Application Serial No. and was amended on

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

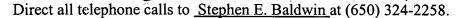
I acknowledge the duty to disclose all information known to me to be material to patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: (none)

Prior Foreign Application(s)			Priority Claimed	
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No	December 27, 1996 D.) (Filing Date)	(Status)(patented, pending, abandoned)
08/513,573 (Application Serial No	August 10, 1995 (Filing Date)	Now U.S. Patent No. 5,656,985 (Status)(patented, pending, abandoned)



Address all correspondence to:

## TRIAL & TECHNOLOGY LAW GROUP A Professional Law Corporation 545 Middlefield Road, Suite 220 Menlo Park, CA 94025

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, United States Code, §1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or f	irst inventor: Peter Lu
Inventor's signature:	
Date:	
Residence:	1708 Ingleside Drive, Flower Mound, TX 75028
Citizenship:	U. S. Citizen
Post Office Address:	194 Civic Circle Lewisville, TX 75067
_	oint inventor, if any: <u>Jeffrey Heaton</u>
Inventor's signature:	
Date:	
Residence:	7583 Normandy Way Cupertino, CA 95014
Citizenship:	U. S. Citizen
Post Office Address:	same
Full name of third join	nt inventor, if any: James W. Heaton
Inventor's signature:	
Date:	· <del></del>
Residence:	1963 Fallen Leaf Lane, Los Altos, CA 94024
Citizenship:	U.S. Citizen
Post Office Address:	same

Full name of fourth join	int inventor, if any: Peter Loh Hang Pao		
Inventor's signature:			
Date:	·		
Residence:	10 Carnarvon Road, 8/F, A-1, Kowloon, Hong Kong China		
Citizenship:			
Post Office Address:	same		
	· · · · · · · · · · · · · · · · · · ·		
Full name of fifth join	t inventor, if any: Robert Loke Hang Lam		
Inventor's signature:			
Date:			
Residence:	Flat A, 6/F, Block 3, Wonderland Villas, N.T., Kowloon, Hong Kong		
Citizenship:	Hong Kong		
Post Office Address:	same		
	. ·		
-	t inventor, if any: Tsang Kei Sun		
Inventor's signature:			
Date: Residence:	Flat F, 19/F, Tower One, Belvedere Garden, Phase Two, Tsuen Wan, Kowloon, Hong Kong		
Citizenship:	Hong Kong		
Post Office Address:	same		